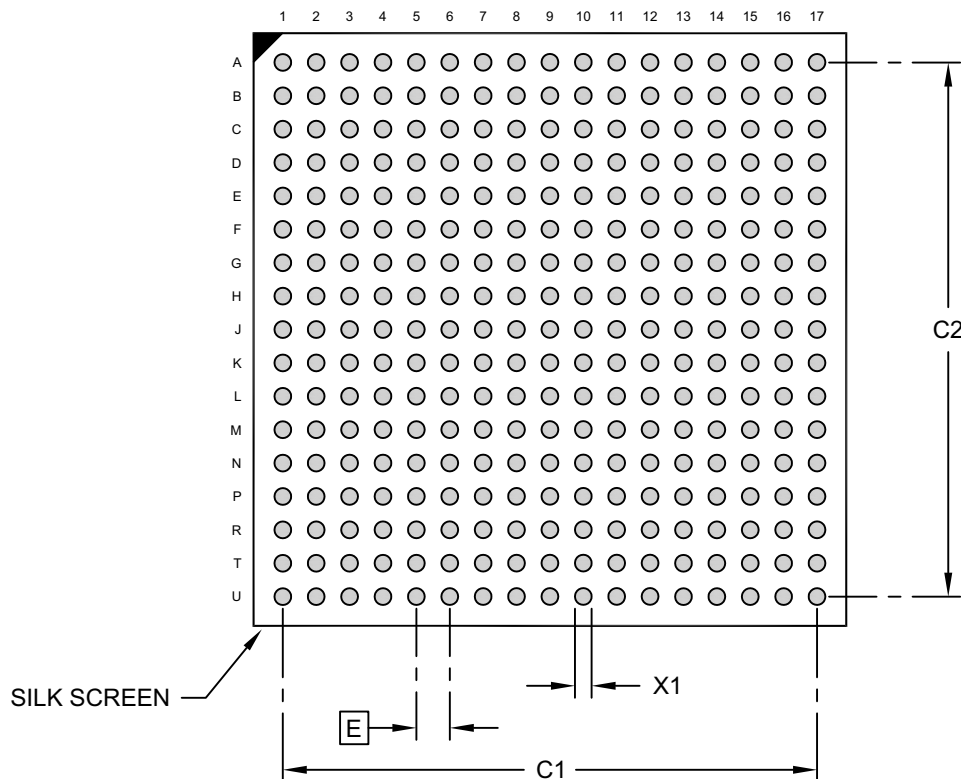


289-Ball Low Profile Fine Pitch Ball Grid Array (AMB) - 14x14x1.4 mm Body [LFBGA] Atmel Legacy Global Package Code CCZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		12.80	
Contact Pad Spacing	C2		12.80	
Contact Pad Width (X20)	X1			0.40

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process